

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

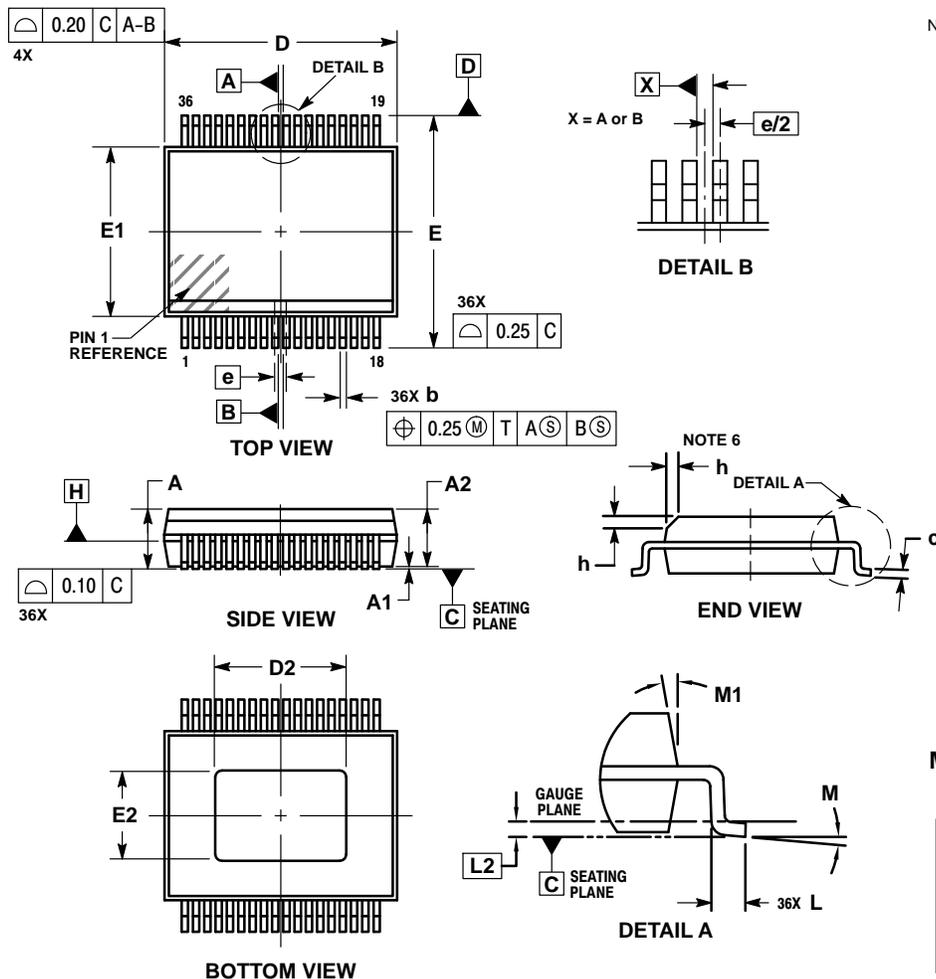
ON Semiconductor®



SCALE 1:1

SSOP36 EP
CASE 940AB
ISSUE A

DATE 19 JAN 2016

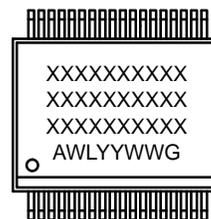


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE *b* DIMENSION AT MMC.
4. DIMENSION *b* SHALL BE MEASURED BETWEEN 0.10 AND 0.25 FROM THE TIP.
5. DIMENSIONS *D* AND *E1* DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. DIMENSIONS *D* AND *E1* SHALL BE DETERMINED AT DATUM *H*.
6. THIS CHAMFER FEATURE IS OPTIONAL. IF IT IS NOT PRESENT, A PIN ONE IDENTIFIER MUST BE LOCATED WITHIN THE INDICATED AREA.

MILLIMETERS		
DIM	MIN	MAX
A	---	2.65
A1	---	0.10
A2	2.15	2.60
b	0.18	0.30
c	0.23	0.32
D	10.30 BSC	
D2	5.70	5.90
E	10.30 BSC	
E1	7.50 BSC	
E2	3.90	4.10
e	0.50 BSC	
h	0.25	0.75
L	0.50	0.90
L2	0.25 BSC	
M	0° - 8°	
M1	5° - 15°	

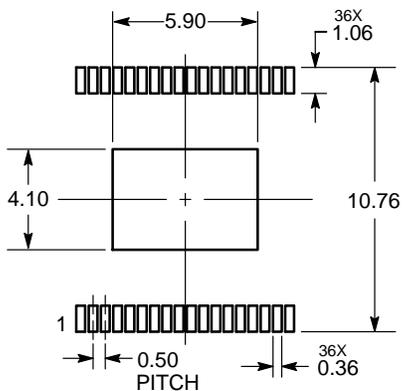
GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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NEW STANDARD:		
DESCRIPTION:	SSOP36 EXPOSED PAD	PAGE 1 OF 2

